

LN75X

GaAlAs Infrared Light Emitting Diode

For optical control systems

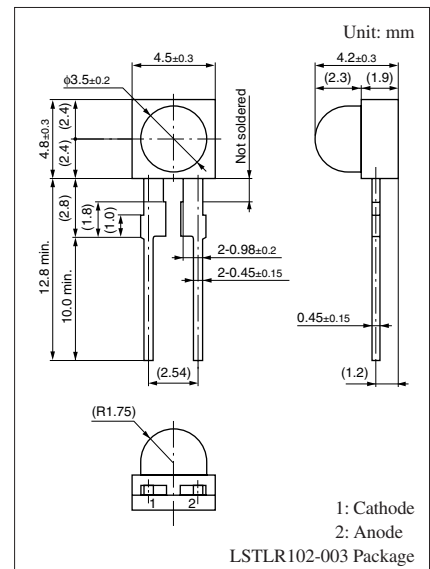
■ Features

- High-power output, high-efficiency: $P_O = 10 \text{ mW}$ (typ.)
- High-speed modulation capability: $f_C = 12 \text{ MHz}$

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	3	V
Forward current	I_F	100	mA
Pulse forward current *	I_{FP}	1	A
Power dissipation	P_D	180	mW
Operating ambient temperature	T_{opr}	-25 to $+85$	$^\circ\text{C}$
Storage temperature	T_{stg}	-30 to $+100$	$^\circ\text{C}$

Note) *: $f = 100 \text{ Hz}$, Duty Cycle = 0.1%



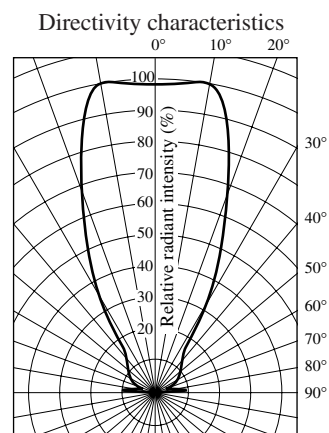
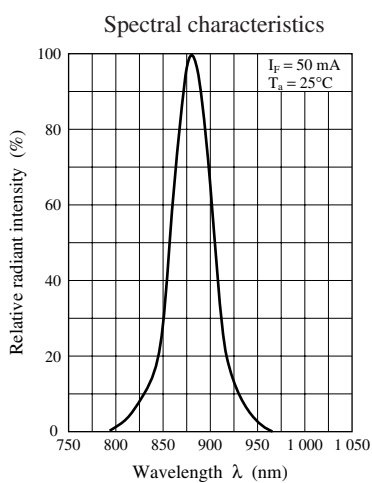
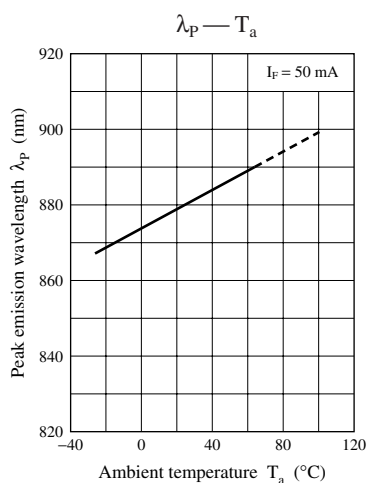
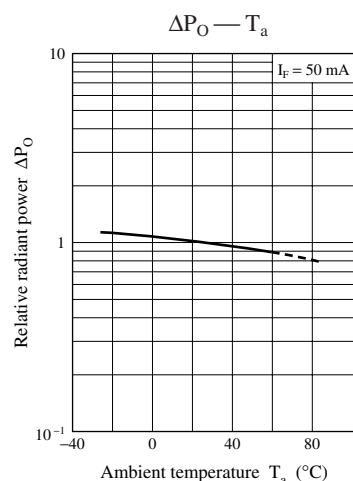
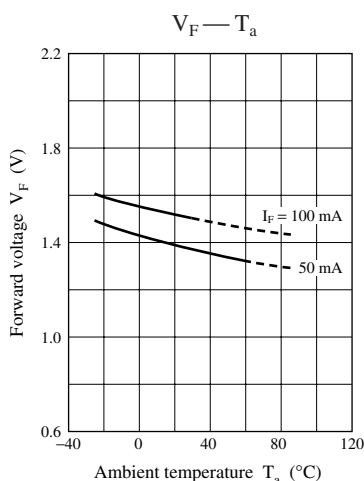
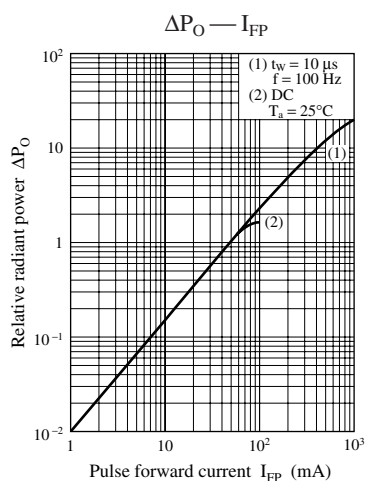
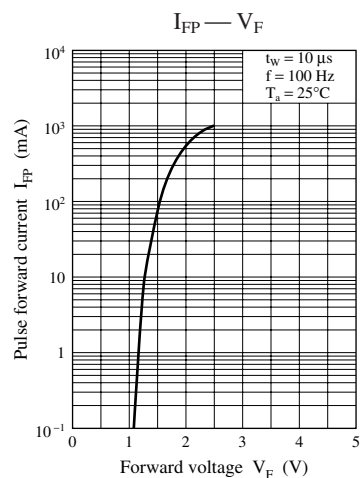
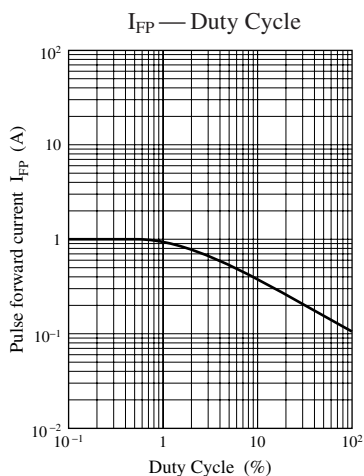
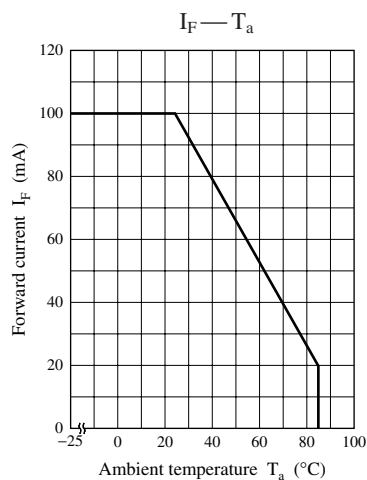
■ Electrical-Optical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 100 \text{ mA}$		1.5	1.8	V
Reverse current	I_R	$V_R = 3 \text{ V}$			10	μA
Radiant power	P_O	$I_F = 50 \text{ mA}$	6	10		mW
Peak emission wavelength	λ_P	$I_F = 50 \text{ mA}$		880		nm
Spectral half band width	$\Delta\lambda$	$I_F = 50 \text{ mA}$		50		nm
Terminal capacitance	C_t	$V_R = 0 \text{ V}$, $f = 1 \text{ MHz}$		50		pF
Half-power angle	θ	The angle when the radiant power is halved		25		$^\circ$

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Cutoff frequency: 12 MHz

$$f_C: 10 \times \log \frac{P_O \text{ at } f = f_C}{P_O \text{ at } f = 1 \text{ MHz}} = -3$$



Caution for Safety

 **DANGER**

■ This product contains Gallium Arsenide (GaAs).

GaAs powder and vapor are hazardous to human health if inhaled or ingested. Do not burn, destroy, cut, cleave off, or chemically dissolve the product. Follow related laws and ordinances for disposal. The product should be excluded from general industrial waste or household garbage.

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